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(54) Title: HIGH TEMPERATURE CERAMIC SOCKET CONFIGURED TO TEST PACKAGED SEMICONDUCTOR DEVICES

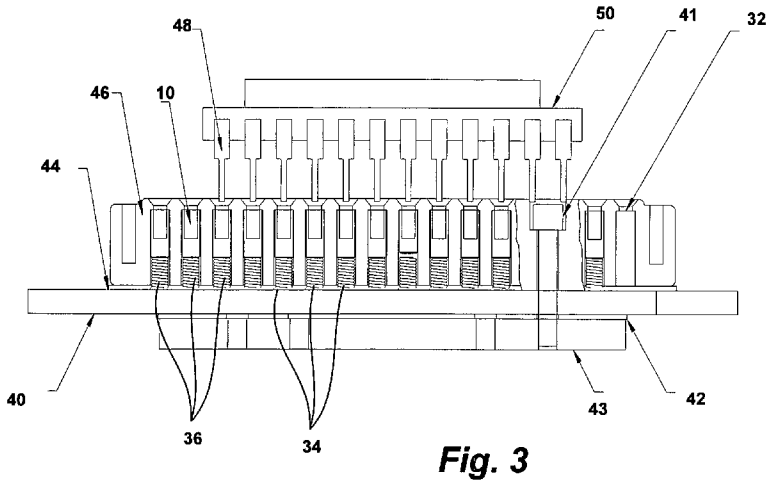

Fig. 3

(57) Abstract: A test socket assembly is for use in testing integrated circuits. A single piece socket is formed substantially of an insulating material and having a plurality of holes formed therein configured to receive a plurality of electrically conductive springs. Each hole of the single piece socket has therein a separate one of the electrically conductive springs. A test socket includes a plurality of pins configured to receive leads of an integrated circuit, the pins of the test socket extending into the plurality of holes of the single piece socket with each pin engaging a spring, wherein the single piece socket is positioned on a circuit board with the plurality of holes being in alignment with electrical contacts on the circuit board such that the plurality of springs are electrically interconnecting the contacts and the plurality of pins. The single-piece socket is comprised substantially of a high-temperature insulating material, such as ceramic.

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